

University of New Mexico
Department of Electrical and Computer Engineering

ECE 520 - VLSI Design (spring 2007)

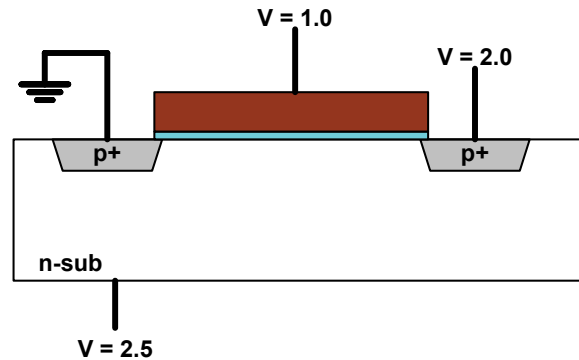
Midterm Exam

Name: _____

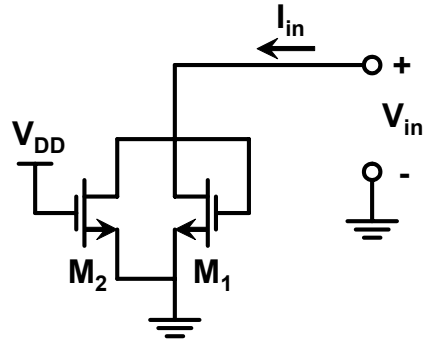
Date: March 7, 2007

Note: Only one 8½ inch by 11 inch page equation sheet, ruler, calculator, pencils, and pens are allowed.

1. (10 points) The following figure is cross section view of an MOS device.
 - (a) What type is this device (NMOS or PMOS)?
 - (b) Considering the potential of each terminal in this figure, determine Source, Drain, Gate, and Substrate terminals and label them on the diagram.
 - (c) Assuming that $|V_T| = 0.5$ v and $|V_{DSAT}| = 1.5$ v. Find the region of operation of the device. Ignore body effect.
 - (d) Determine drain current if $|K'| = 100 \mu A/v^2$, $(W/L) = 10$, and $|\lambda| = 0.1 v^{-1}$.
 - (f) Draw depletion region and the channel on the diagram. What is the potential across the channel in this device?



2. (15 points) The following circuit is a **linear** resistor implemented by NMOS only. Assume that M1 and M2 are identical.
- (a) Find I_{in} as a function of V_{in} assuming $V_T < V_{in} < V_{DD} - V_T$ (assume long channel device and ignore channel length modulation).
- (b) What is the dynamic resistance of this active resistor ($R_d = \partial V_{in} / \partial I_{in}$)?
- (c) What is the expression for total parasitic capacitance of this active resistor as a function of C_{OX} , C_J , C_{JSW} , A_D , P_D , C_{GSOV} , C_{GDOV} of M1 and M2?



3. (15 points) For a MOSFET operating in the subthreshold regime ($V_{GS} < V_T$), the reduction in gate voltage needed to reduce the drain current by one decade is defined as the “subthreshold swing” where

$$S = \frac{kT}{q} \ln(10) \left(1 + \frac{C_{Dep}}{C_{OX}} \right)$$

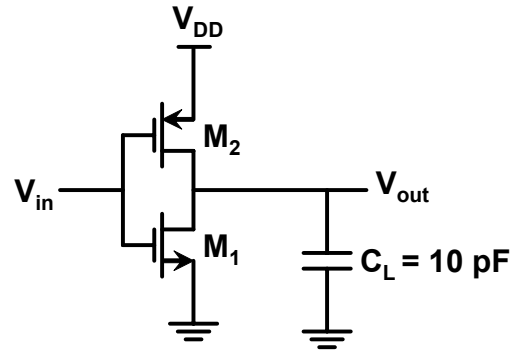
The unit of S is mV/decade.

- (a) Find S at room temperature for an NMOS with $t_{OX} = 2 \text{ nm}$, $W_{Dep} = 40 \text{ nm}$ ($\epsilon_{SiO2} = 3.9$ and $\epsilon_{Si} = 11.9$).
- (b) The threshold voltage for this device is defined to V_{GS} at which the normalized drain current $I_{DS}/(W/L)$ reaches 100 nA , with $V_{DS} = V_{DD} = 2.5 \text{ V}$. We would like to set the leakage current to be 1 nA when $V_{GS} = 0 \text{ V}$ and $V_{DS} = V_{DD} = 2.5 \text{ V}$ for a device with $(W/L)=5$. What is the minimum threshold voltage this device can have?
- (c) This device is used in a circuit that can go to standby mode. To meet the power dissipation requirement in standby mode, a body bias is applied. Considering that the zero bias threshold voltage of the device is 0.1 v , find the body bias that is needed to be applied. Draw a circuit diagram of the NMOS and Indicate the polarity of body bias voltage on your diagram. Assume $\gamma = 0.4 \text{ v}^{1/2}$ and $2\phi_f = 0.6 \text{ v}$.

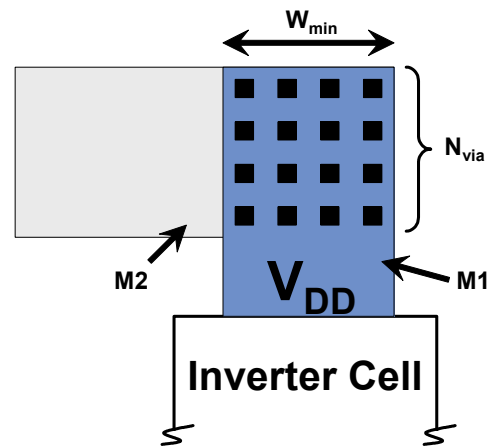
4. (20 points) We would like to design an inverter to drive a long interconnect (clock line) with effective capacitance of **10 pF**. By computing the average current used to charge/discharge C_L , determine W_p such that $t_{PLH} = 250 \text{ ps}$. Notice that the load capacitance is substantially larger than the internal capacitance of the gate. To reduce the parasitics, use minimum length for all transistors ($L=0.25 \text{ um}$). Supply voltage V_{DD} is **2.5 v**.

Use the following data table for all transistors. Watch for channel length modulation and velocity saturation!

$$\begin{aligned} K'_p &= -60 \mu\text{A}/\text{V}^2 \\ V_{Tp0} &= -0.4 \text{ v} \\ \lambda_p &= -0.15 \text{ v}^{-1} \\ V_{DSATp} &= -1 \text{ v} \end{aligned}$$



5. (10 points) We would like to design the layout of the clock driver designed in the previous problem.
- (a) Determine the dynamic power dissipation of the inverter assuming the clock frequency of 1GHz. Ignore the device internal capacitances.
 - (b) Determine the average current of the clock driver.
 - (c) Determine the minimum width of power and ground strap, W_{min} , (shown below) to prevent electromigration. Assume that metal thickness is $0.4 \mu\text{m}$ and maximum current density $J_{max} = 2 \times 10^6 \text{ A/cm}^2$ for copper.
 - (d) Determine the minimum number of vias, N_{via} , (shown below) to prevent electromigration. Assume that via size is $0.25 \mu\text{m} \times 0.25 \mu\text{m}$.



6. (15 points) The circuit in Figure 5-A is used to balance delay from the inverter to block A and B. Since the input capacitance of block B is smaller than that of block A, we try to match the delay by routing a longer wire to block B. Figure 5-B is the equivalent circuit of Figure 5-A.
- Using π -model for wires (see Figure 5-C), determine all R and C values of the equivalent circuit shown in Figure 5-B. Note that C_0 , R_2 , and C_2 will be as a function of L_2 . Assume interconnect resistance is $5 \Omega/\mu\text{m}$ and interconnect capacitance is $0.2 \text{ fF}/\mu\text{m}$.
 - Using the Elmore delay model, write equations for propagation delays from V_{in} to terminal points A and B.
 - Find the length of wire, L_2 , such that the propagation delays become equal.

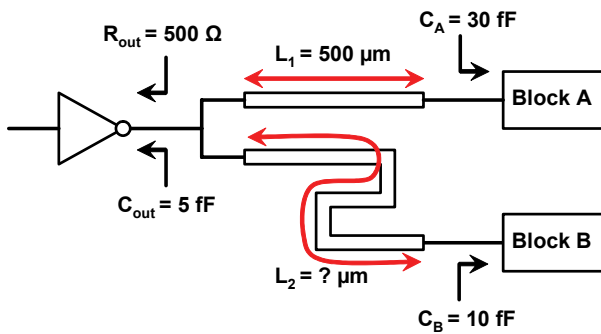


Figure 5-A

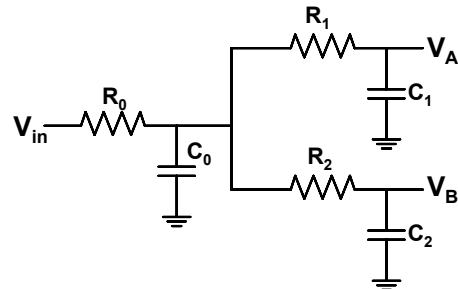


Figure 5-B

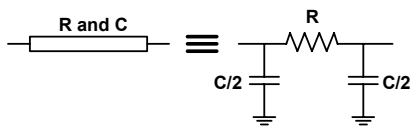


Figure 5-C

7. (3 points) What is the depletion mode transistor? What would be the characteristic of an NMOS depletion mode device?

8. (3 points – *multiple choice*) Due to DIBL effect, by increasing Drain voltage of an NMOS, the threshold voltage

- A- increases.
- B- decreases.
- C- doesn't change.

Explain why?

9. (3 points – *multiple choice*) In order to increase the noise margin of a CMOS inverter, the size of

- A- both NMOS and PMOS should decrease.
- B- both NMOS and PMOS should increase.
- C- transistors doesn't affect noise margin.
- D- PMOS should increase and NMOS should decrease.
- F- PMOS should decrease and NMOS should increase.

Explain why?

10. (3 points) Intel has recently announced that their fab is capable of implementing metal gate and high-k dielectric in their CMOS processes. Explain how metal gate and high-k dielectric improves VLSI technology.

11. (3 points) What is Salicidation in CMOS process? How does it improve the device performance?